

Product Summary

BV_{DSS}	R_{D(S)} Max	I_D Max T_A = +25°C
30V	12mΩ @ V _{GS} = 10V	10A
	16mΩ @ V _{GS} = 4.5V	8.5A

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{D(S)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

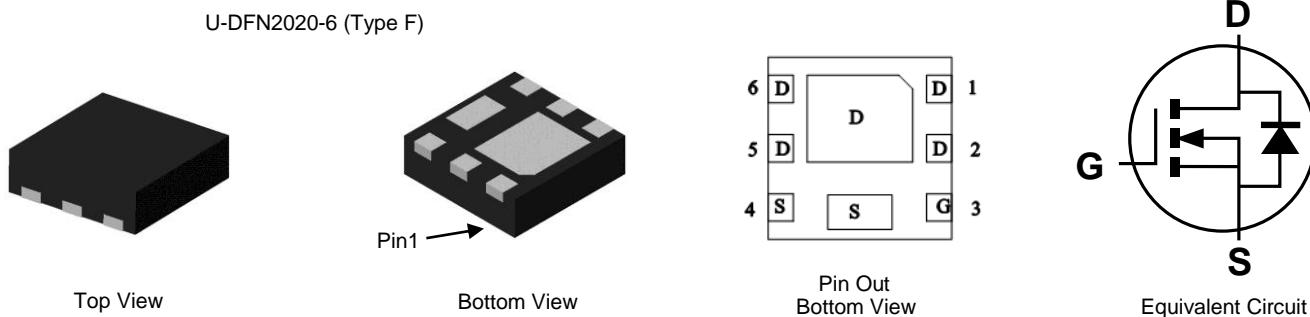
- Battery Management Application
- Power Management Functions
- DC-DC Converters

Features and Benefits

- 0.6mm Profile – Ideal for Low Profile Applications
- PCB Footprint of 4mm²
- Low Gate Threshold Voltage
- Low On-Resistance
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at <https://www.diodes.com/products/automotive/automotive-products/>.
- This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability. <https://www.diodes.com/quality/product-definitions/>

Mechanical Data

- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 e4
- Weight: 0.0065 grams (Approximate)



Ordering Information (Note 4)

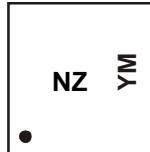
Part Number	Case	Packaging
DMN3016LFDF-7	U-DFN2020-6 (Type F)	3,000/Tape & Reel
DMN3016LFDF-13	U-DFN2020-6 (Type F)	10,000/Tape & Reel

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information

Site 1



NZ = Product Type Marking Code
YM = Date Code Marking
Y = Year (ex: G = 2019)
M = Month (ex: 9 = September)

Date Code Key

Year	2017	2018	2019	2020	2021	2022	2023	2024	2025
Code	E	F	G	H	I	J	K	L	M
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep
Code	1	2	3	4	5	6	7	8	9
	Oct	Nov	Dec						
	O	N	D						

Site 2



NZ = Product Type Marking Code
YW = Date Code Marking
Y = Year (ex: 9 = 2019)
W = Week (ex: a = Week 27; z Represents Week 52 and 53)
X = Internal Code (ex: U = Monday)

Date Code Key

Year	2019	2020	2021	2022	2023	2024	2025	2026
Code	9	0	1	2	3	4	5	6

Week	1-26	27-52	53
Code	A-Z	a-z	z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	T	U	V	W	X	Y	Z

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic			Symbol	Value	Unit	
Drain-Source Voltage			V_{DSS}	30	V	
Gate-Source Voltage			V_{GSS}	± 20	V	
Continuous Drain Current (Note 6) $V_{GS} = 10\text{V}$	Steady State	$T_A = +25^\circ\text{C}$	I_D	10	A	
		$T_A = +70^\circ\text{C}$		8		
	$t < 10\text{s}$	$T_A = +25^\circ\text{C}$	I_D	12	A	
		$T_A = +70^\circ\text{C}$		9		
Maximum Continuous Body Diode Forward Current (Note 6)			I_S	2.5	A	
Pulsed Drain Current (10 μs Pulse, Duty Cycle = 1%)			I_{DM}	50	A	
Avalanche Current (Note 7) $L = 0.1\text{mH}$			I_{AR}	22	A	
Avalanche Energy (Note 7) $L = 0.1\text{mH}$			E_{AR}	24	mJ	

 Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$T_A = +25^\circ\text{C}$	P_D	0.73	W
	$T_A = +70^\circ\text{C}$		0.47	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	174	$^\circ\text{C/W}$
	$t < 10\text{s}$		121	
Total Power Dissipation (Note 6)	$T_A = +25^\circ\text{C}$	P_D	2.02	W
	$T_A = +70^\circ\text{C}$		1.30	
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	66	$^\circ\text{C/W}$
	$t < 10\text{s}$		42	
Thermal Resistance, Junction to Case (Note 6)	Steady State	$R_{\theta JC}$	11.6	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}		-55 to +150	

 Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV_{DSS}	30	—	—	V	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	μA	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	$V_{GS(TH)}$	1.4	—	2.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	8	12	$\text{m}\Omega$	$V_{GS} = 10\text{V}, I_D = 11\text{A}$
		—	12	16		$V_{GS} = 4.5\text{V}, I_D = 9\text{A}$
Diode Forward Voltage	V_{SD}	—	0.70	1.0	V	$V_{GS} = 0\text{V}, I_S = 1\text{A}$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C_{iss}	—	1415	—	pF	$V_{DS} = 15\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	—	119	—		
Reverse Transfer Capacitance	C_{rss}	—	82	—		
Gate Resistance	R_g	—	2.6	—	Ω	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$
Total Gate Charge ($V_{GS} = 4.5\text{V}$)	Q_g	—	11.3	—	nC	$V_{DS} = 15\text{V}, I_D = 12\text{A}$
Total Gate Charge ($V_{GS} = 10\text{V}$)	Q_g	—	25.1	—		
Gate-Source Charge	Q_{gs}	—	3.5	—		
Gate-Drain Charge	Q_{gd}	—	3.6	—		
Turn-On Delay Time	$t_{D(ON)}$	—	4.8	—	ns	$V_{DD} = 15\text{V}, V_{GS} = 10\text{V}, R_L = 1.25\Omega, R_g = 3\Omega$
Turn-On Rise Time	t_r	—	16.5	—		
Turn-Off Delay Time	$t_{D(OFF)}$	—	26.1	—		
Turn-Off Fall Time	t_f	—	5.6	—		
Reverse Recovery Time	t_{RR}	—	12.3	—	ns	$ I_F = 12\text{A}, di/dt = 500\text{A}/\mu\text{s}$
Reverse Recovery Charge	Q_{RR}	—	10.4	—	nC	

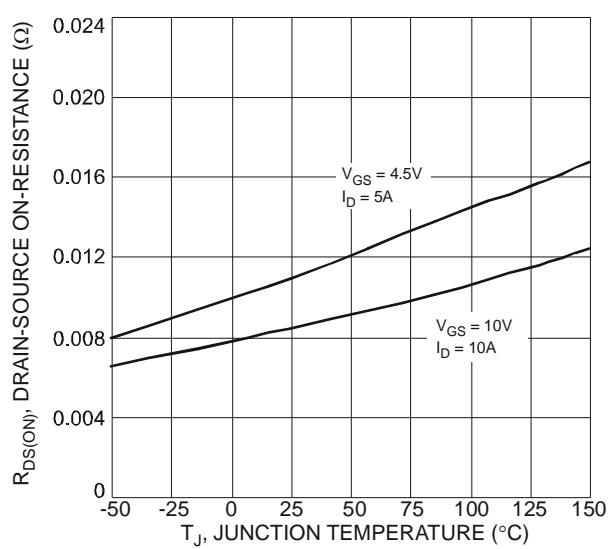
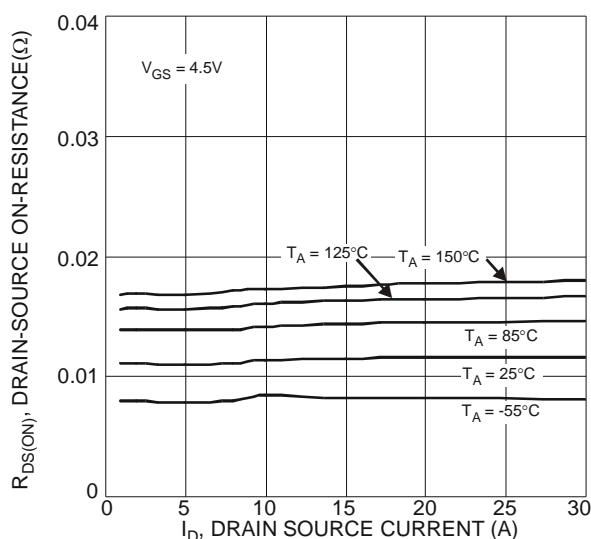
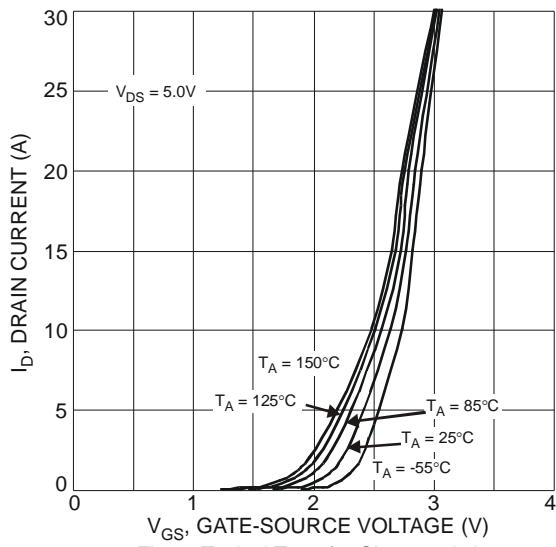
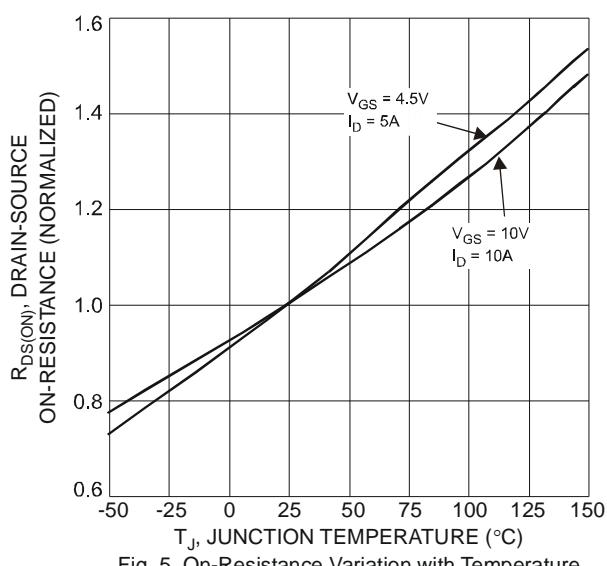
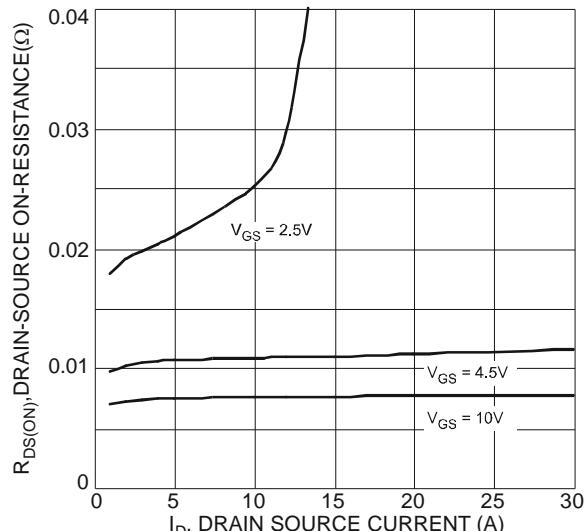
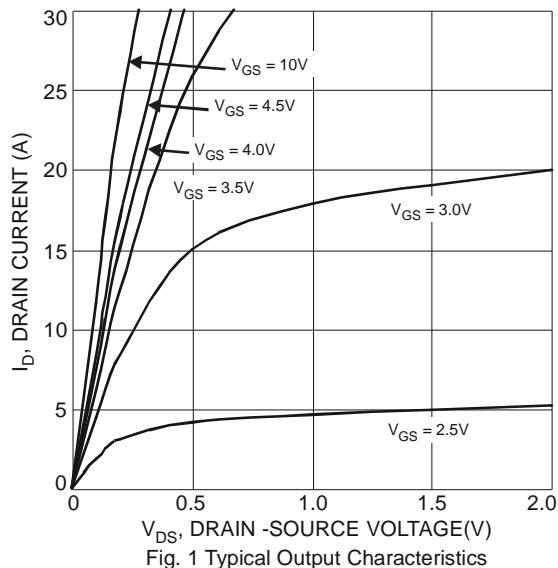
Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

7. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25^\circ\text{C}$.

8. Short duration pulse test used to minimize self-heating effect.

9. Guaranteed by design. Not subject to product testing.



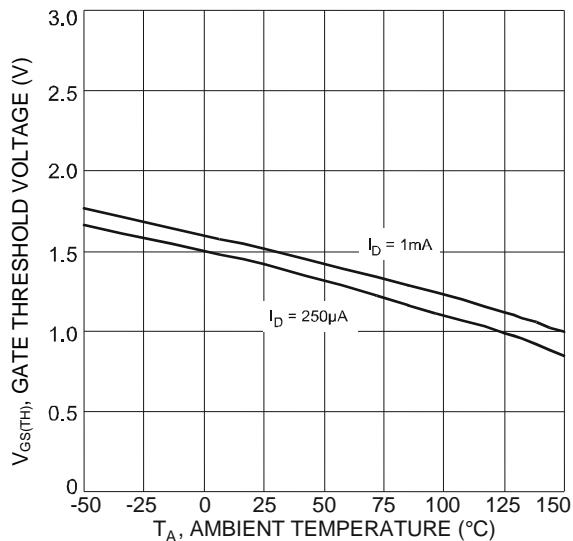


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

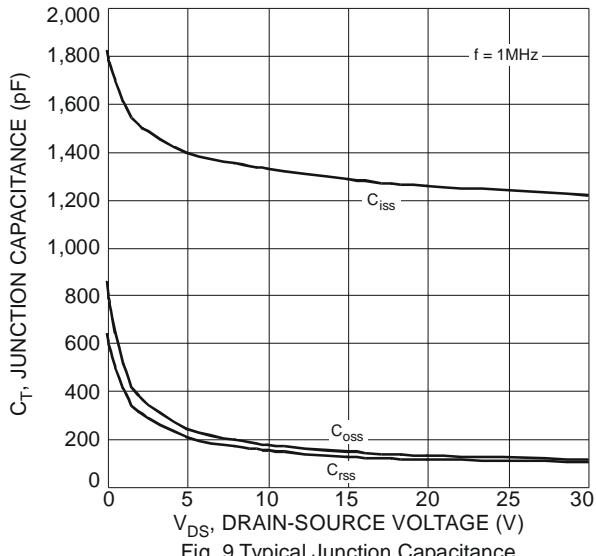


Fig. 9 Typical Junction Capacitance

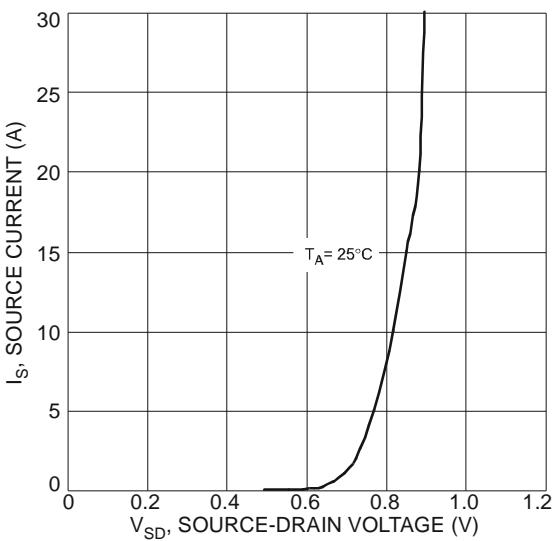


Fig. 8 Diode Forward Voltage vs. Current

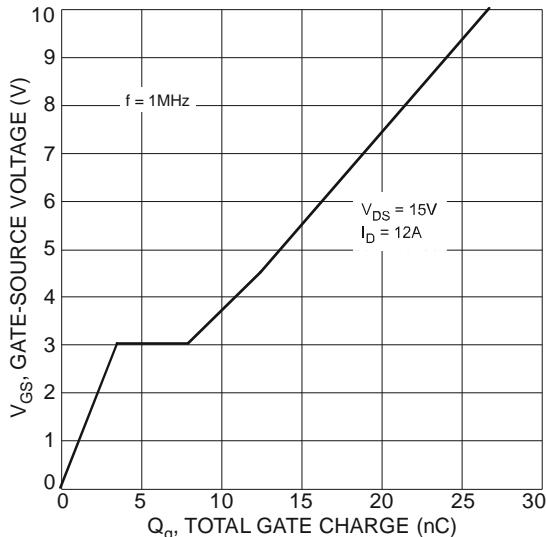


Fig. 10 Gate-Charge Characteristics

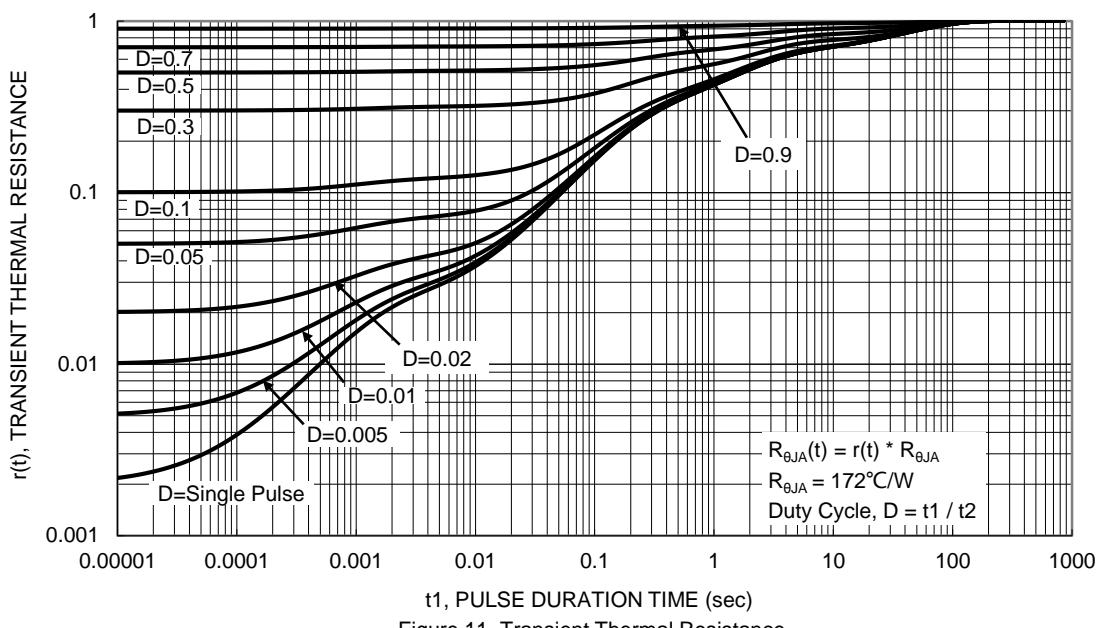
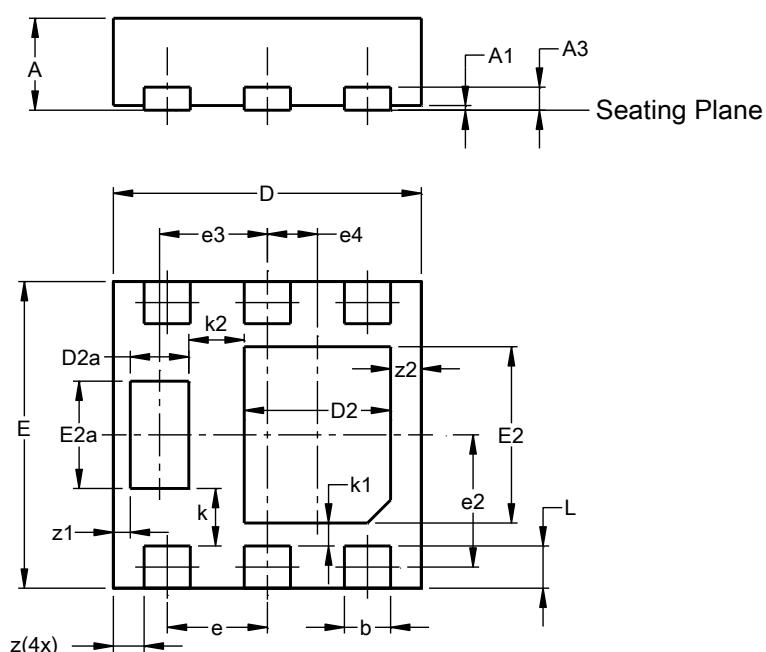


Figure 11. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN2020-6 (Type F)

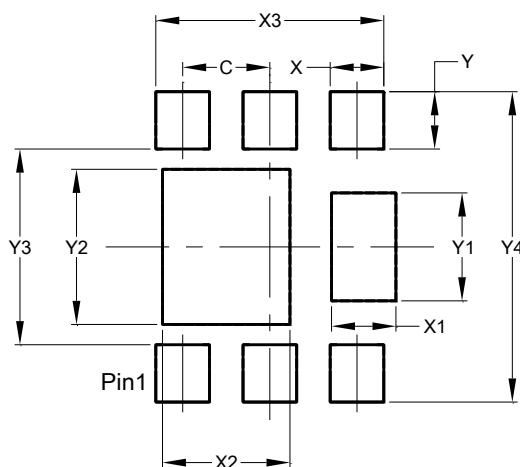


U-DFN2020-6 (Type F)			
Dim	Min	Max	Typ
A	0.57	0.63	0.60
A1	0.00	0.05	0.03
A3	-	-	0.15
b	0.25	0.35	0.30
D	1.95	2.05	2.00
D2	0.85	1.05	0.95
D2a	0.33	0.43	0.38
E	1.95	2.05	2.00
E2	1.05	1.25	1.15
E2a	0.65	0.75	0.70
e	0.65 BSC		
e2	0.863 BSC		
e3	0.70 BSC		
e4	0.325 BSC		
k	0.37 BSC		
k1	0.15 BSC		
k2	0.36 BSC		
L	0.225	0.325	0.275
z	0.20 BSC		
z1	0.110 BSC		
z2	0.20 BSC		
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN2020-6 (Type F)



Dimensions	Value (in mm)
C	0.650
X	0.400
X1	0.480
X2	0.950
X3	1.700
Y	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300

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